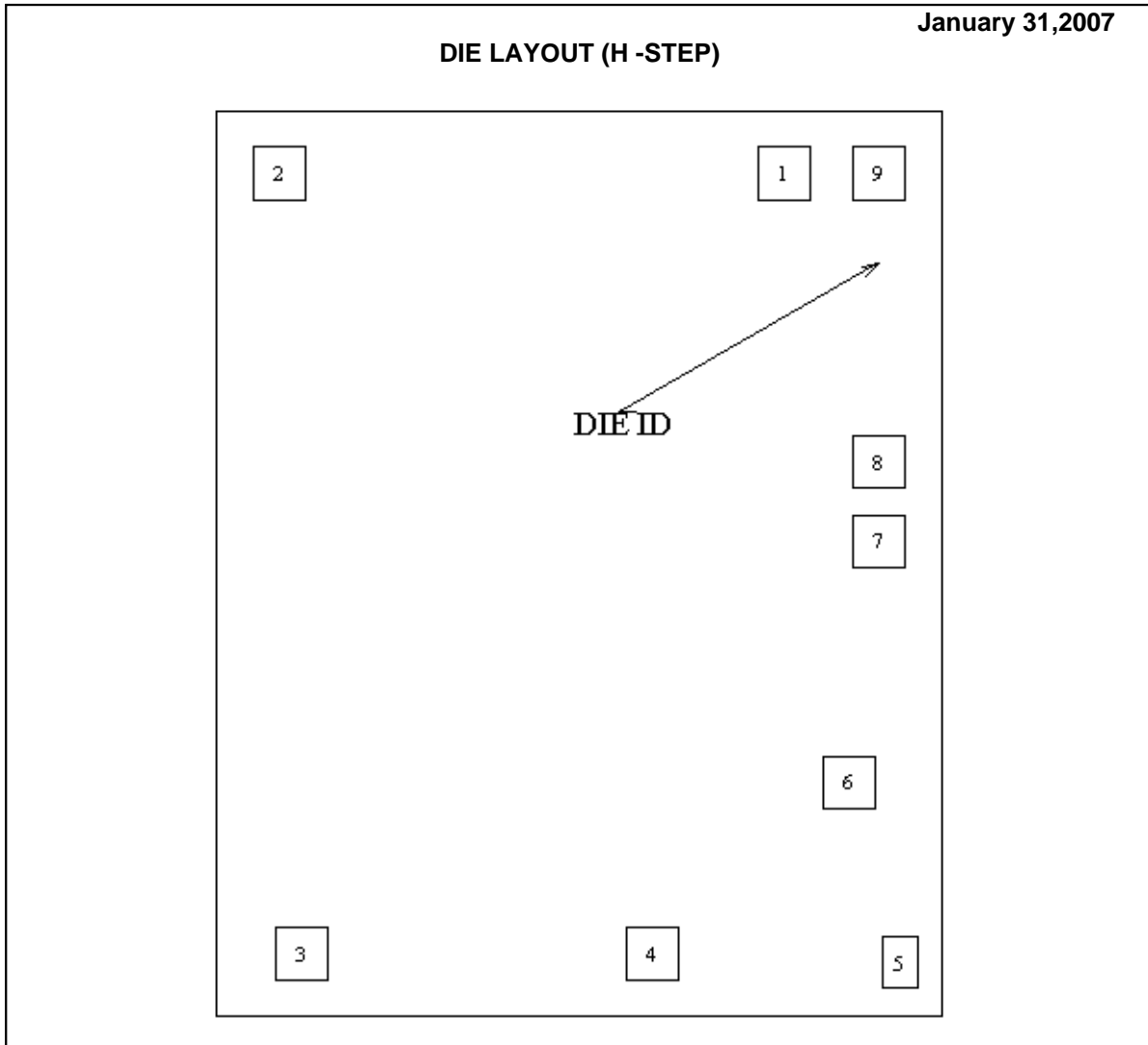


**LF398 MDC MWC
MONOLITHIC SAMPLE AND HOLD CIRCUIT**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LF198	Bond Pad Opening Size (min)	117µm x 117µm
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1626µm x 2032µm 64.0mils x 80.0mils	Back Side Connection	Floating
Thickness	330µm		
Min Pitch	127µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (H -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE	
		X	Y	X	Y
Input	1	460	876	117/117	
V-	2	-672	876	117/117	
Output	3	-622	-876	117/117	
CH	4	165	-876	117/117	
NC	5	718	-895	79.5/117	
Logic Ref	6	607	-490	117/117	
Logic	7	673	51	117/117	
V+	8	673	229	117/117	
Offset Adjust	9	673	876	117/117	

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